

QIAOXIN N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(on)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

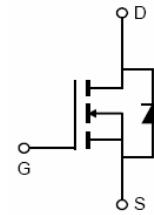
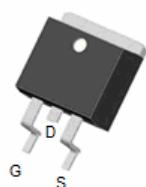
General Features

- $V_{DS} = 120V, I_D = 70A$
- $R_{DS(on)} = 8.5\text{m}\Omega$, typical (TO-220)@ $V_{GS} = 10V$
- $R_{DS(on)} = 8.2\text{m}\Omega$, typical (TO-263)@ $V_{GS} = 10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

TO-220



TO-263



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package
VCRR10N12	VCRR10N12	TO-220
VCRR10N12D	VCRR10N12D	TO-263

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	70	A
Drain Current-Continuous($T_C = 100^\circ\text{C}$)	$I_D(100^\circ\text{C})$	50	A
Pulsed Drain Current	I_{DM}	280	A
Maximum Power Dissipation	P_D	120	W
Derating factor		0.8	$\text{W}/^\circ\text{C}$
Single pulse avalanche energy ^(Note 4)	E_{AS}	352	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.25	°C/W
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	120		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=120\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=35\text{A}$	TO-220	-	8.5	10.0
			TO-263		8.2	10.0
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=35\text{A}$		60	-	S
Dynamic Characteristics (Note 3)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	3050	-	pF
Output Capacitance	C_{oss}		-	280	-	pF
Reverse Transfer Capacitance	C_{rss}		-	22	-	pF
Switching Characteristics (Note 3)						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=60\text{V}, I_{\text{D}}=35\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=1.6\Omega$	-	15	-	nS
Turn-on Rise Time	t_r		-	10	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	34	-	nS
Turn-Off Fall Time	t_f		-	8	-	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=60\text{V}, I_{\text{D}}=35\text{A}, V_{\text{GS}}=10\text{V}$	-	53	-	nC
Gate-Source Charge	Q_{gs}		-	20	-	nC
Gate-Drain Charge	Q_{gd}		-	12.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 2)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=35\text{A}$	-	-	1.2	V
Diode Forward Current	I_{S}		-	-	70	A
Reverse Recovery Time	t_{rr}	$T_{\text{J}} = 25^\circ\text{C}, I_{\text{F}} = 35\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ (Note 3)	-	60	-	nS
Reverse Recovery Charge	Q_{rr}		-	106	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
3. Guaranteed by design, not subject to production
4. EAS condition : $T_j=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, L=0.25\text{mH}, R_g=25\Omega$

Typical Electrical and Thermal Characteristics

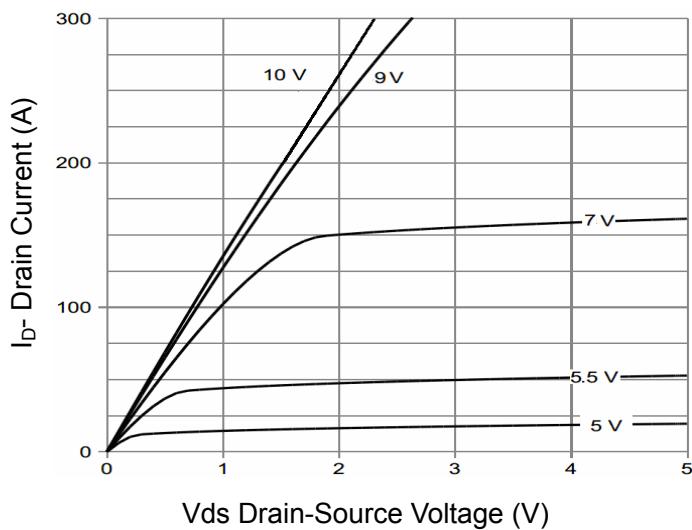


Figure 1 Output Characteristics

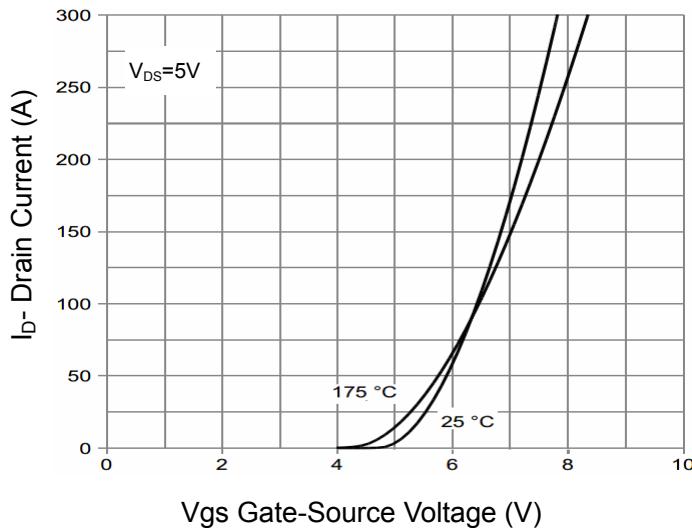


Figure 2 Transfer Characteristics

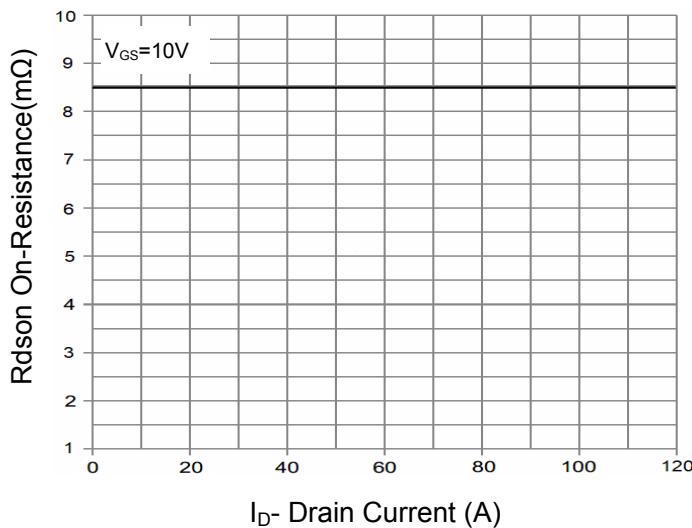


Figure 3 Rdson- Drain Current

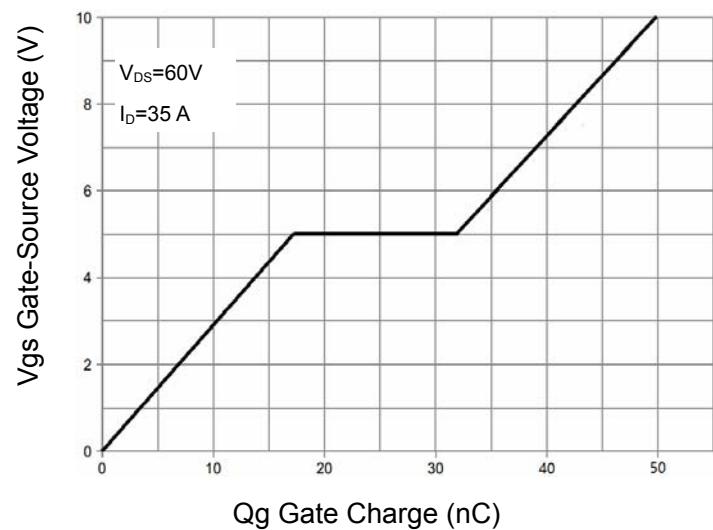


Figure 4 Gate Charge

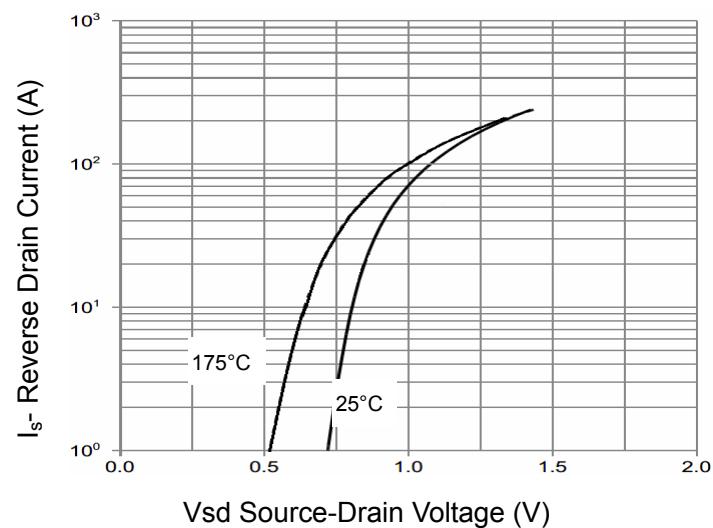


Figure 5 Source- Drain Diode Forward

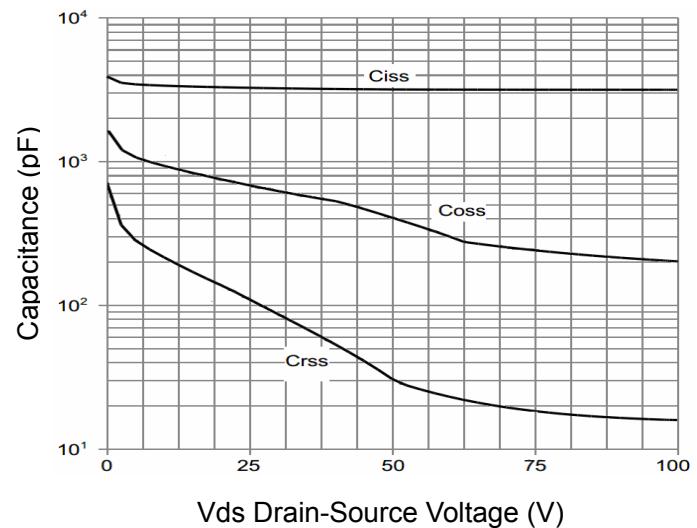


Figure 6 Capacitance vs Vds

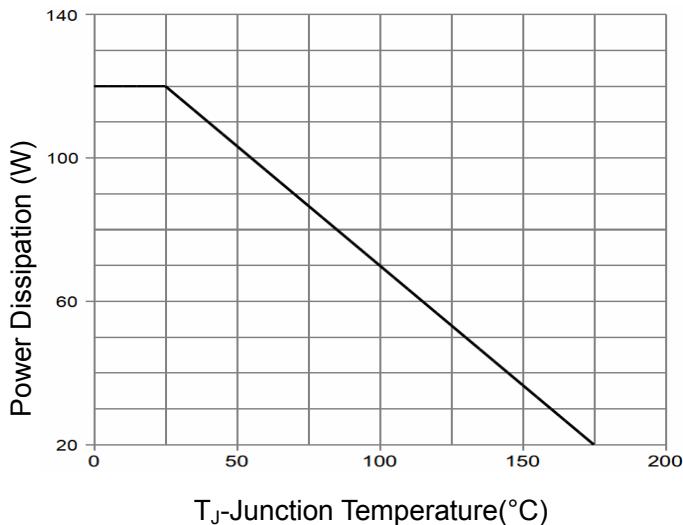


Figure 7 Power De-rating

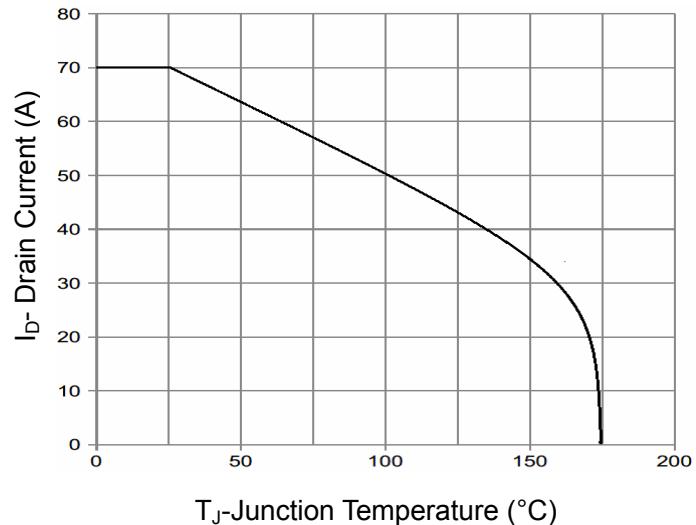


Figure 9 Current De-rating

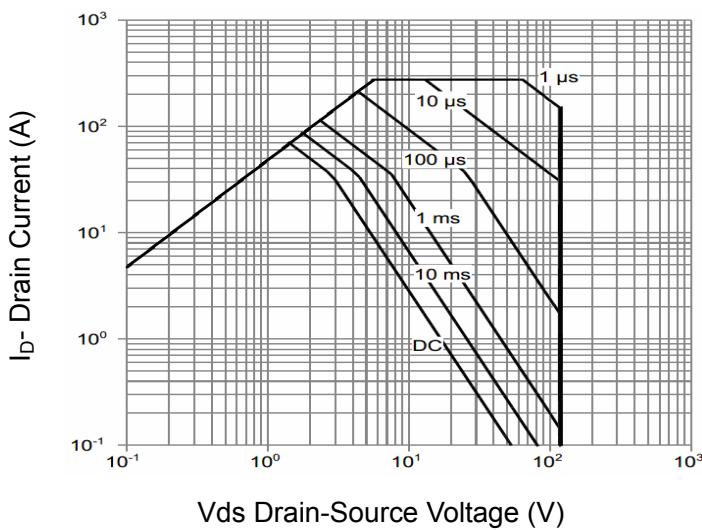


Figure 8 Safe Operation Area

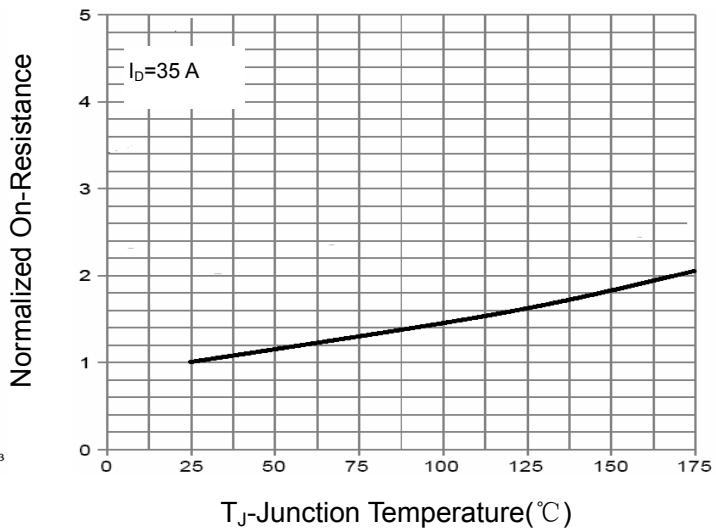


Figure 10 Rdson-Junction Temperature

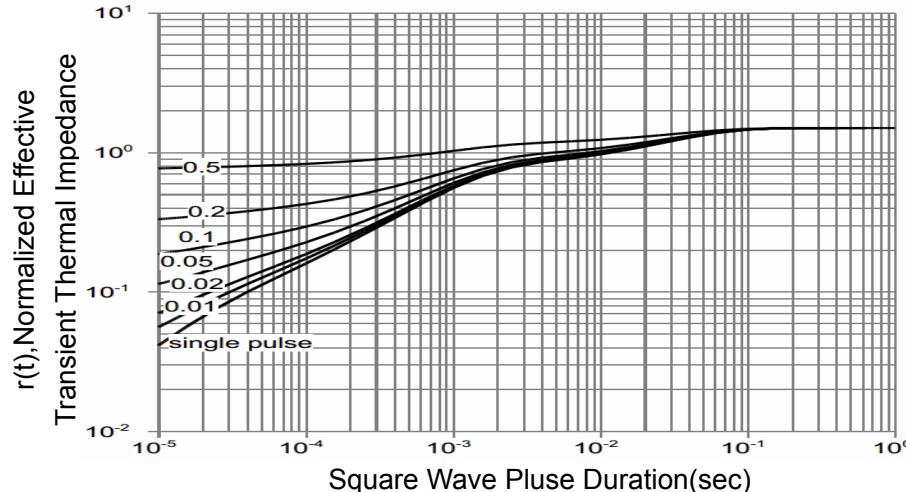
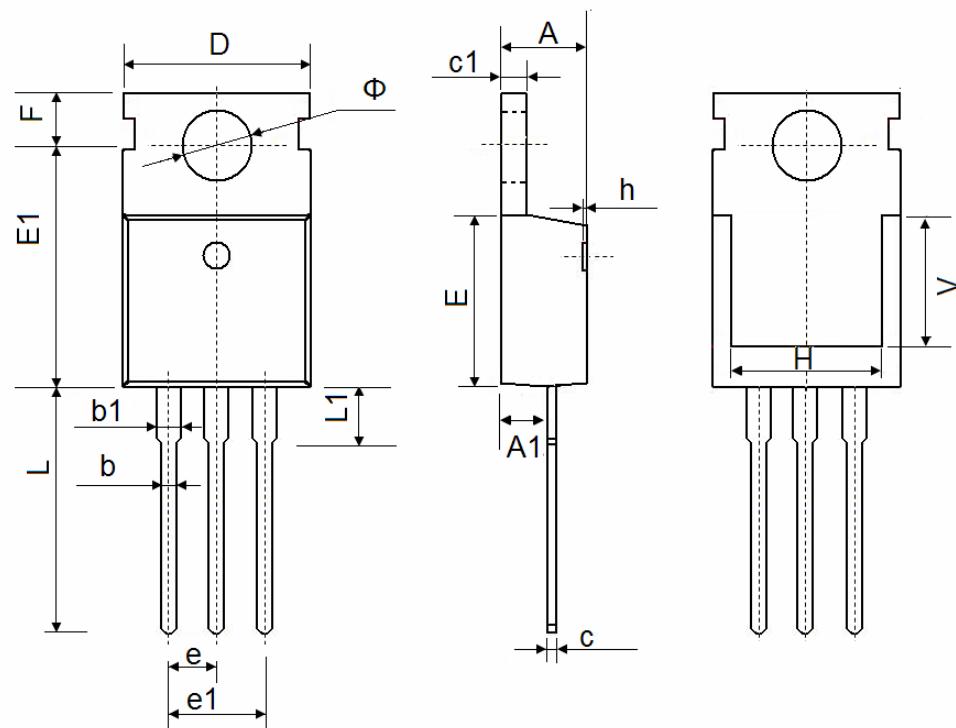


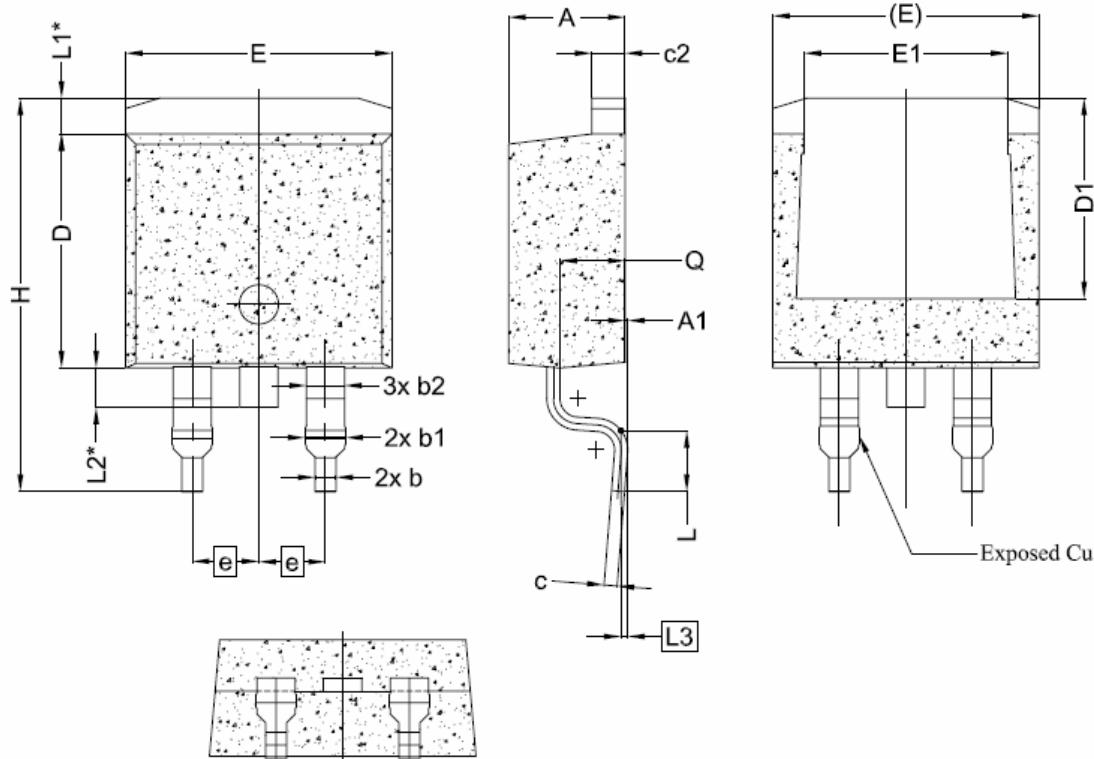
Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150

TO-263-2L Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	4.24	4.44	4.64
A1	0.00	0.10	0.25
b	0.70	0.80	0.90
b1	1.20	1.55	1.75
b2	1.20	1.45	1.70
c	0.40	0.50	0.60
c2	1.15	1.27	1.40
D	8.82	8.92	9.02
D1	6.86	7.65	-
E	9.96	10.16	10.36
E1	6.89	7.77	7.89
e	2.54BSC		
H	14.61	15.00	15.88
L	1.78	2.32	2.79
L1	1.36 REF.		
L2	1.50 REF.		
L3	0.25 BSC		
Q	2.30	2.48	2.70

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